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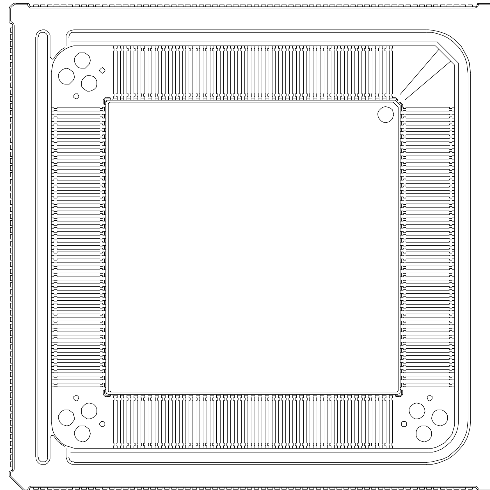
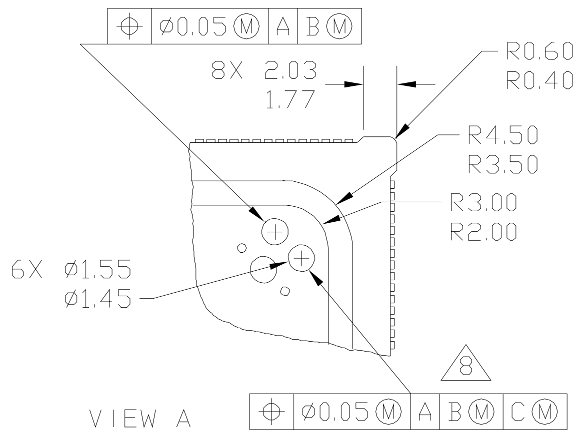
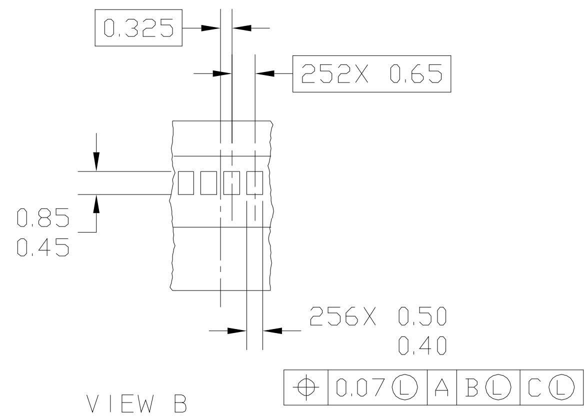
TITLE: 160 LD QFP WITH 256 LD AB MOLDED CARRIER RING	DOCUMENT NO: 98ASB42876B REV: C
	STANDARD: NON-JEDEC
	SOT1698-1 19 JAN 2016



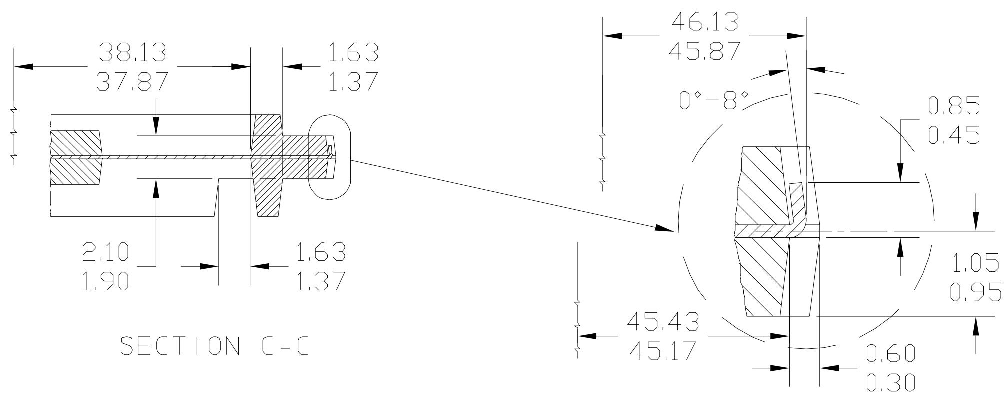
BOTTOM VIEW OF UNIT
IN MOLDED CARRIER RING



VIEW A



VIEW B



SECTION C-C

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:

160 LD QFP WITH 256 LD
AB MOLDED CARRIER RING

DOCUMENT NO: 98ASB42876B REV: C

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NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M−1994.

2. CONTROLLING DIMENSION: MILLIMETER

3. (△) DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.20 PER SIDE.

4. (△) DIMENSIONS INCLUDE MOLD MISMATCH, AND ARE MEASURED AT THE PARTING LINE.

5. UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE SYMMETRICAL ABOUT CENTERLINES.

6. (△) DATUM HOLES B AND C ARE TO BE USED FOR TRIM, FORM AND EXCISE OF THE MOLDED PACKAGE ONLY.

7. (△) HOLES Q1 AND Q2 ARE TO BE USED FOR ELECTRICAL TESTING ONLY.

8. (△) NON−DATUM HOLES ONLY.

9. (△) APPLIES TO RING AND PACKAGE FEATURES.

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